



VMDSEMI

VTTD065R17BNA

Datasheet



VMDSEMI

General Description

Symbol

$V_{(BR)DSS}$	$R_{DS(ON)_{max}}$	I_D
650V	1.7Ω@10V	7A

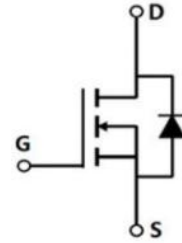


Figure 1 Symbol of VTTD065R17BNA

Features

- Trench Technology Power MOSFET
- Low $R_{DS(ON)}$
- Low Gate Charge
- Low Gate Resistance
- 100% UIS Tested
- 100% ΔV_{DS} Tested

Package Type

Application

- Power Switching Application

TO-220-3L-F

Figure 2 Package Type of VTTD065R17BNA

Ordering Information

Product Name	Package
VTTD065R17BNA	TO-220-3L-F

Absolute Maximum Ratings ($T_A = 25\text{ °C}$, unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DSS}	650	V
Gate-Source Voltage	V_{GSS}	± 30	V
Continuous Drain Current ^{Note1}	I_D	7	A
Pulsed Drain Current ^{Note2}	I_{DM}	28	
Avalanche Current ^{Note3}	I_{AS}	17.5	
Single Pulsed Avalanche Energy ^{Note3}	E_{AS}	76.5	mJ
Total Power Dissipation ^{Note5}	P_D	50	W
Junction Temperature	T_J	150	°C
Storage Temperature	T_{STG}	-55 to 150	°C

Thermal Resistance

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Ambient ^{Note6}	$R_{\theta JA}$		65		°C/W
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$		2.5		°C/W

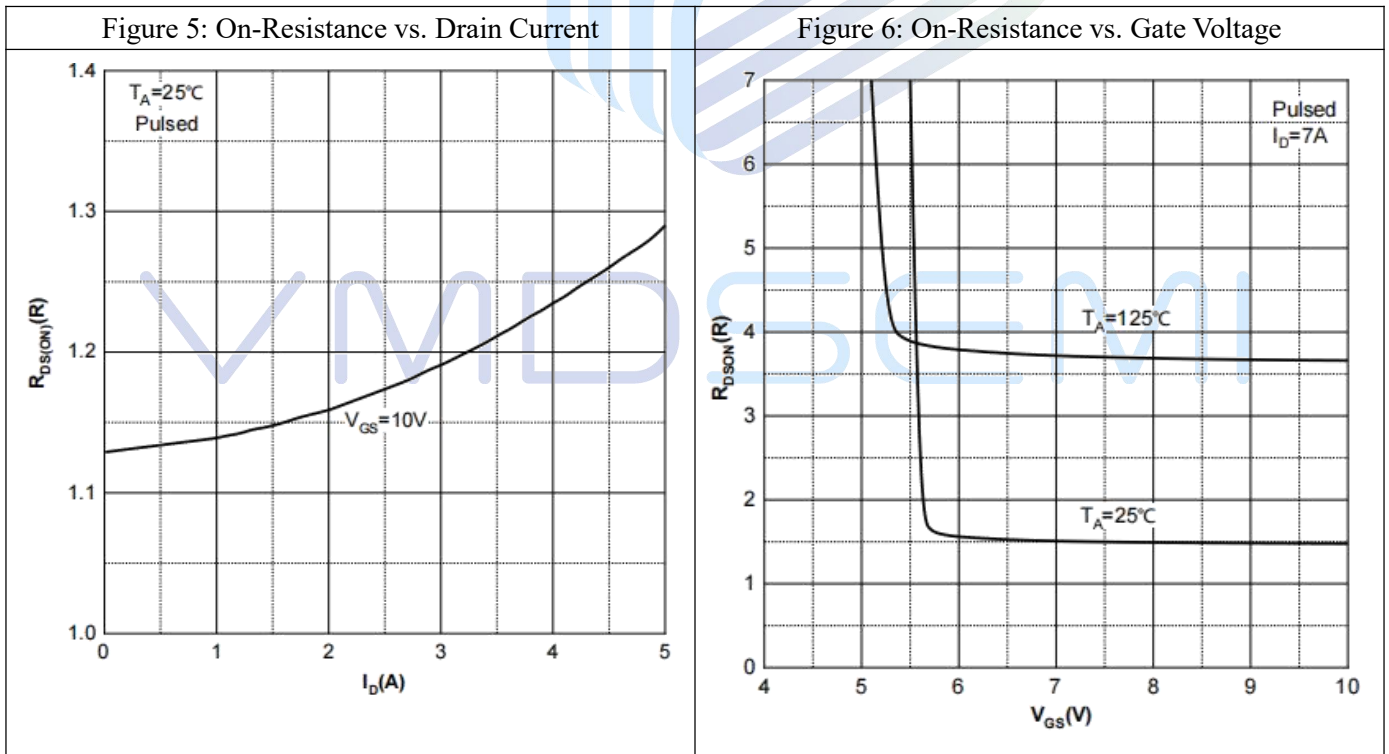
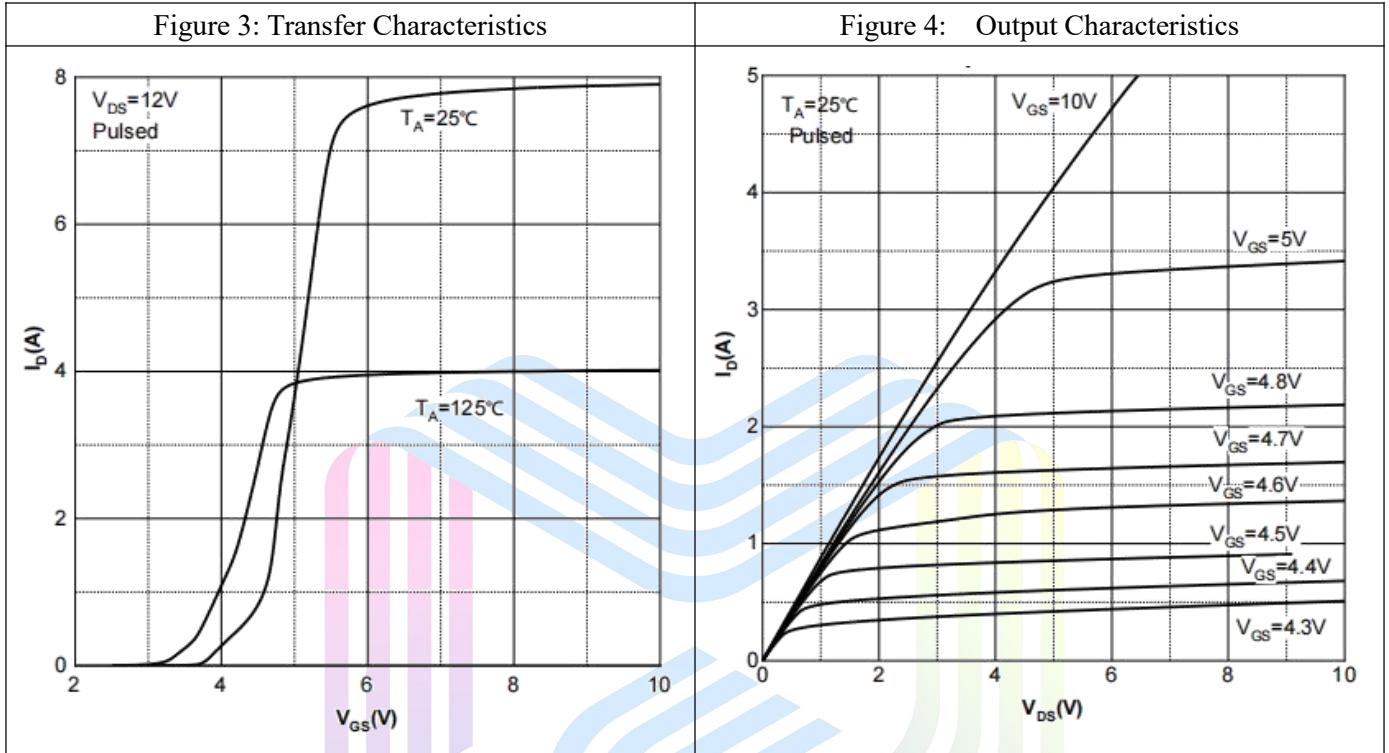


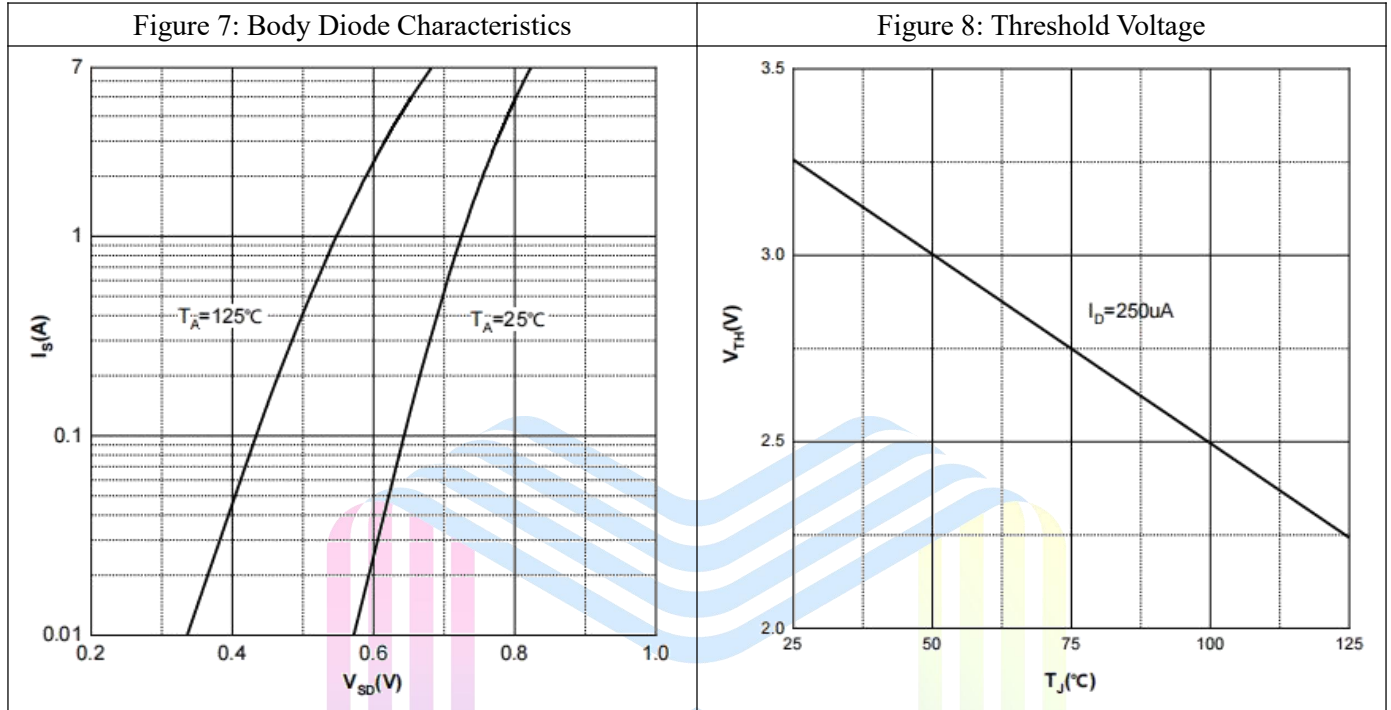
1.7Ω, 650V, N-Channel Power MOSFET
VTTD065R17BNA
Electrical Characteristics ($T_J = 25\text{ }^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Statistic Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	650			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=650V, V_{GS}=0V$			1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS} = \pm 30V, V_{DS}=0V$			± 100	nA
Gate Threshold Voltage ^{Note4}	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	2	3.2	4	V
Static Drain-Source On-Resistance ^{Note4}	$R_{DS(ON)}$	$V_{GS}=10V, I_D=1A$		1.2	1.7	Ω
Dynamic Characteristics						
Input Capacitance	C_{ISS}	$V_{DS}=45V$		1170		pF
Output Capacitance	C_{OSS}	$V_{GS}=0V$		63.9		pF
Reverse Transfer Capacitance	C_{RSS}	$f=1MHz$		2.6		pF
Total Gate Charge	Q_g	$V_{DS}=335V$		17.1		nC
Gate-Source Charge	Q_{gs}	$V_{GS}=10V$		0.6		
Gate-Drain Charge	Q_{gd}	$I_D=1A$		3.6		
Gate Resistance	R_g	$f=1MHz, \text{Open drain}$		2.1		Ω
Switching Parameters						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=300V$ $I_D=2A$ $R_G=25\Omega$		33.6		ns
Turn-on Rise Time	t_r			7.2		
Turn-off Delay Time	$t_{d(off)}$			64		
Turn-off Fall Time	t_f			31.2		
Diode Characteristics						
Diode Forward Voltage ^{Note4}	V_{SD}	$V_{GS}=0V, I_S=2A$			1.2	V

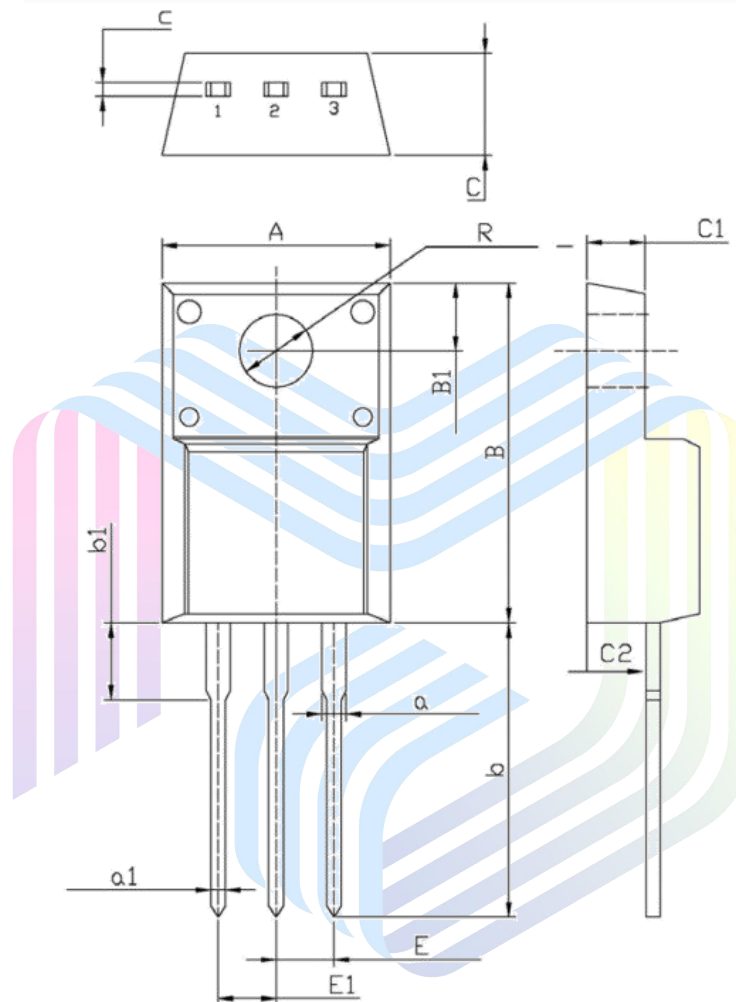
Notes :

- 1.The maximum current rating is limited by package.And device mounted on a large heatsink.
- 2.Pulse Test : Pulse Width $\leq 10\mu s$, duty cycle $\leq 1\%$.
3. E_{AS} condition: $V_{DD} = 100V, V_{GS} = 10V, L = 0.5mH, R_G=25\Omega$ Starting $T_J = 25^\circ C$.
- 4.Pulse Test : Pulse Width $\leq 300\mu s$, duty cycle $\leq 2\%$.
- 5.The power dissipation P_D is limited by $T_{J(MAX)} = 150^\circ C$.And device mounted on a large heatsink
- 6.Device mounted on $1in^2$ FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ C$.

Typical Performance Characteristics




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Mechanical Dimensions:
TO-220-3L-F Package Information


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
C	4.500	4.900	0.177	0.193
c	0.400	0.600	0.016	0.024
A	9.960	10.360	0.392	0.408
B	15.670	16.070	0.617	0.633
B1	3.300	3.500	0.130	0.138
R	3.080	3.280	0.121	0.129
b	12.480	13.480	0.491	0.531
b1	2.900	3.900	0.114	0.154
a	1.080	1.480	0.043	0.058
a1	0.700	0.900	0.028	0.035
E	2.340	2.740	0.092	0.108
E1	2.340	2.740	0.092	0.108
C1	2.340	2.740	0.092	0.108
C2	2.560	2.960	0.101	0.117

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